

Aerospace Adhesives

NEW PRODUCT LAUNCH

EPIBOND® 100 A/B Adhesive

New Composite Bonding Adhesive from Huntsman Advanced Materials

Epibond® 100 A/B is a two-component, heat-curing epoxy structural adhesive designed for demanding applications requiring high hot / wet Tg performance, and elevated temperature performance. Easy to mix and apply, Epibond® 100 A/B bonds composites and dissimilar substrates such as carbon fiber, glass reinforced composite, PEEK and aluminum. Available in dual syringe 50 ML and 200 ML cartridges for easy use. Does not intentionally contain any Substances of Very High Concern (SVHC) as defined under REACH.

Key Features

2:1 (pbv) mix ratio
Thixotropic paste with spacer beads
100-120 minutes working time
Moderate heat cure cycle
Service temperatures up to 300° F
High Tg, lap shear strength

Key Benefits

Easy to process by hand or cartridge
Gap filling allows versatile use with uniform bond line
Long working time allows for large composite part assembly
Variable handling strengths
Retention of properties under demanding hot / wet conditions

Contact your sales representative or distributor for a sample today.

Epibond® is a registered trademark of Huntsman Corporation or an affiliate thereof in one or more, but not all countries.

Huntsman Advanced Materials

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